

Low Voltage Hex Inverter with 5 V Tolerant Inputs

74LCX04

General Description

The LCX04 contains six inverters. The inputs tolerate voltages up to 5.5 V allowing the interface of 5 V systems to 3 V systems.

The 74LCX04 is fabricated with advanced CMOS technology to achieve high speed operation while maintaining CMOS low power dissipation.

Features

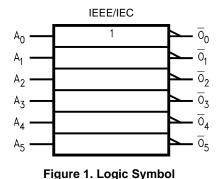
- 5 V Tolerant Inputs
- 1.65 V-5.5 V V_{CC} Specifications Provided
- 5.2 ns t_{PD} Max. ($V_{CC} = 3.3 \text{ V}$), 10 μ A I_{CC} Max.
- Power Down High Impedance Inputs and Outputs
- ± 24 mA Output Drive ($V_{CC} = 3.0 \text{ V}$)
- Implements Proprietary Noise/EMI Reduction Circuitry
- Latch-up Performance Exceeds JEDEC 78 Conditions
- ESD Performance:
 - ♦ Human Body Model > 2000 V
- Leadless DQFN Package
- These Devices are Pb-Free, Halide Free and are RoHS Compliant

PIN DESCRIPTION

Pin Name	Description	
A _n , B _n	Inputs	
\overline{O}_n	Outputs	
DAP	No Connect	

^{1.} DAP (Die Attach Pad)

Logic Symbol



MARKING DIAGRAMS



ZXYKK XXXXXX

XXXXXX = Specific Device Code = Assembly Plant Code XY = Date Code (Year & Week) = Lot Run Traceability Code ΚK



TSSOP-14 WB **DT SUFFIX CASE 948G**

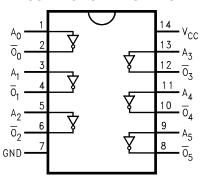


XXXXXX = Specific Device Code = Assembly Location

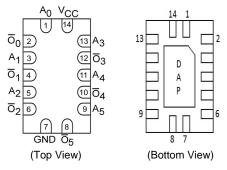
= Wafer Lot = Year W = Work Week = Pb-Free Package

(Note: Microdot may be in either location)

CONNECTION DIAGRAMS



Pin Assignments for TSSOP



Pad Assignments for DQFN

ORDERING INFORMATION

See detailed ordering and shipping information on page 6 of this data sheet.

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter		Value	Unit
V _{CC}	DC Supply Voltage		-0.5 to +6.5	V
VI	DC Input Voltage (Note 2)		-0.5 to +6.5	V
Vo	DC Output Voltage (Note 2)	C Output Voltage (Note 2) Active–Mode (High or Low State)		V
		Tri-State Mode	-0.5 to +6.5	1
		Power–Down Mode (V _{CC} = 0 V)	-0.5 to +6.5	1
I _{IK}	DC Input Diode Current	V _I < GND	-50	mA
lok	DC Output Diode Current V _O < GND		-50	mA
Io	DC Output Source/Sink Current		±50	mA
I _{CC} or I _{GND}	DC Supply Current per Supply Pin or Ground Pin		±100	mA
T _{STG}	Storage Temperature Range		-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for	10 Seconds	260	°C
TJ	Junction Temperature under Bias		+150	°C
$\theta_{\sf JA}$	Thermal Resistance (Note 2)	QFN14	130	°C/W
		TSSOP-14	150	1
P _D	Power Dissipation in Still Air at 125°C	QFN14	962	mW
		TSSOP-14	833	1
MSL	Moisture Sensitivity		Level 1	
F _R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
V _{ESD}	ESD Withstand Voltage (Note 4)	Human Body Model	2000	V
		Charged Device Model	N/A	1

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 2. I_O absolute maximum rating must be observed.
- Measured with minimum pad spacing on an FR4 board, using 76 mm-by-114 mm, 2-ounce copper trace no air flow per JESD51-7.
 HBM tested to EIA / JESD22-A114-A. CDM tested to JESD22-C101-A. JEDEC recommends that ESD qualification to EIA/JESD22-A115A (Machine Model) be discontinued.

RECOMMENDED OPERATING CONDITIONS

Symbol		Parameter	Min	Тур	Max	Unit
V _{CC}	Supply Voltage	Operating	1.65	3.3	5.5	V
		Data Retention Only	1.5	3.3	5.5	1
VI	Digital Input Voltage	•	0	-	5.5	V
Vo	Output Voltage	Active Mode (High or Low State)	0	-	V _{CC}	V
		Tri-State Mode	0	-	5.5	1
		Power Down Mode (V _{CC} = 0 V)	0	-	5.5	
T _A	Operating Free–Air Temperature		-40	-	+125	°C
t _r , t _f	Input Rise or Fall Rate	V _{CC} = 1.65 V to 1.95 V	0	-	20	nS/V
		V _{CC} = 2.3 V to 2.7 V	0	-	20	1
		V_{IN} from 0.8 V to 2.0 V, V_{CC} = 3.0 V	0	-	10	1
		V _{CC} = 4.5 V to 5.5 V	0	-	5	1

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

5. Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

74LCX04

DC ELECTRICAL CHARACTERISTICS

				$T_A = -40^{\circ}$	C to +85°C	T _A = -40°C	to +125°C	
Symbol	Parameter	Conditions	V _{CC} (V)	Min	Max	Min	Max	Unit
V _{IH}	HIGH Level Input Voltage		1.65–1.95	0.65 x V _{CC}	-	0.65 x V _{CC}	-	V
			2.3–2.7	1.7	-	1.7	-	
			3.0-3.6	2.0	-	2.0	-	
			4.5–5.5	0.70 x V _{CC}	-	0.70 x V _{CC}	-	
V _{IL}	LOW Level Input Voltage		1.65–1.95	-	0.35 x V _{CC}	_	0.35 x V _{CC}	V
			2.3–2.7	-	0.7	_	0.7	
			3.0-3.6	_	0.8	_	0.8	
			4.5–5.5	-	0.30 x V _{CC}	_	0.30 x V _{CC}	
V _{OH}	High-Level Output Voltage	$V_I = V_{IH} \text{ or } V_{IL}$ $I_{OH} = -100 \mu A$	1.65–5.5	V _{CC} - 0.1	_	V _{CC} - 0.1	_	V
		$I_{OH} = -4 \text{ mA}$	1.65	1.29	-	1.29	_	
		$I_{OH} = -8 \text{ mA}$	2.3	1.8	-	1.8	-	
		$I_{OH} = -12 \text{ mA}$	2.7	2.2	_	2.2	_	
		$I_{OH} = -16 \text{ mA}$	3.0	2.4	-	2.4	_	
		$I_{OH} = -24 \text{ mA}$	3.0	2.2	-	2.2	-	
		$I_{OH} = -32 \text{ mA}$	4.5	3.7	_	3.7	_	
V_{OL}	Low-Level Output Voltage	$V_I = V_{IH}$ or V_{IL}						V
		$I_{OL} = 100 \mu A$	1.65–5.5	_	0.1	_	0.1	
		$I_{OL} = 4 \text{ mA}$	1.65	_	0.24	_	0.24	
		$I_{OL} = 8 \text{ mA}$	2.3	_	0.3	_	0.3	
		I _{OL} = 12 mA	2.7	_	0.4	_	0.4	
		I _{OL} = 16 mA	3.0	_	0.4	_	0.4	
		$I_{OL} = 24 \text{ mA}$	3.0	_	0.55	_	0.55	
		$I_{OL} = 32 \text{ mA}$	4.5	_	0.6	_	0.6	
lı	Input Leakage Current	V _I = 0 to 5.5 V	1.65–5.5	-	±5.0	_	±5.0	μΑ
I _{OFF}	Power Off Leakage Current	V _I = 5.5 V or V _O = 5.5 V	0	_	10	-	10	μΑ
I _{CC}	Quiescent Supply Current	V _I = 5.5 V or GND	1.65–5.5	-	10	-	10	μΑ
ΔI_{CC}	Increase in I _{CC} per Input	$V_{IH} = V_{CC} - 0.6 \text{ V}$	2.3-3.6	-	500	-	500	μΑ

AC ELECTRICAL CHARACTERISTICS

				$T_A = -40^{\circ}C$	C to +85°C	T _A = -40°C	to +125°C								
Symbol	Parameter	Test Condition	V _{CC} (V)	Min	Max	Min	Max	Unit							
t _{PLH} , t _{PHL}	Propagation Delay,	See Figures 2	1.65–1.95	-	10	-	10	ns							
	Input to Output	and 3	2.3–2.7	-	6.2	-	6.2								
			2.7	-	6.0	-	6.0								
				l							3.0-3.6	-	5.2	-	5.2
			4.5–5.5	-	4.2	-	4.2								
t _{OSHL} ,	Output to Output Skew		1.65–1.95	-	-	-	-	ns							
toslh			2.3–2.7	-	-	-	-								
			2.7	-	-	-	-								
			3.0-3.6	-	1.0	-	1.0								
			4.5–5.5	-	_	_	-								

74LCX04

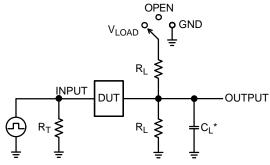
DYNAMIC SWITCHING CHARACTERISTICS

				T _A = +25°C	
Symbol	Parameter	Condition	V _{CC} (V)	Тур	Unit
V _{OLP}	Quiet Output Dynamic Peak V _{OL}	C _L = 50 pF, V _{IH} = 3.3 V, V _{IL} = 0 V	3.3	0.8	V
		C _L = 30 pF, V _{IH} = 2.5 V, V _{IL} = 0 V	2.5	0.6	
V _{OLV}	Quiet Output Dynamic Valley V _{OL}	$C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{ V}, V_{IL} = 0 \text{ V}$	3.3	-0.8	V
		C _L = 30 pF, V _{IH} = 2.5 V, V _{IL} = 0 V	2.5	-0.6	

CAPACITANCE

Symbol	Parameter	Condition	Тур	Unit
C _{IN}	Input Capacitance	V_{CC} = Open, V_I = 0 V or V_{CC}	7	pF
C _{OUT}	Output Capacitance	$V_{CC} = 3.3 \text{ V}, V_{I} = 0 \text{ V or } V_{CC}$	8	pF
C _{PD}	Power Dissipation Capacitance	$V_{CC} = 3.3 \text{ V}, V_{I} = 0 \text{ V or } V_{CC}, f = 10 \text{ MHz}$	25	pF

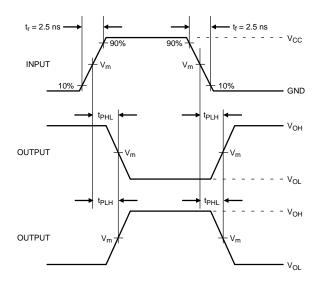
AC Loading and Waveforms (Generic for LCX Family)

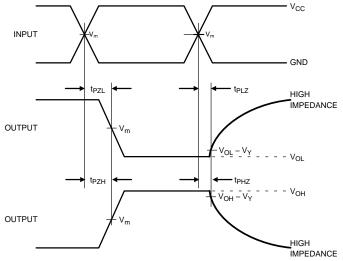


Test	Switch Position
t _{PLH} / t _{PHL}	Open
t _{PLZ} / t _{PZL}	V_{LOAD}
t _{PHZ} / t _{PZH}	GND

 C_L includes probe and jig capacitance R_T is Z_{OUT} of pulse generator (typically 50 $\Omega)$ f = 1 MHz, t_W = 500 ns

Figure 2. Test Circuit





V _{CC} , V	R_L,Ω	C _L , pF	V _{LOAD}	V _m , V	V _Y , V
1.65 to 1.95	500	30	2 x V _{CC}	V _{CC} / 2	0.15
2.3 to 2.7	500	30	2 x V _{CC}	V _{CC} / 2	0.15
2.7	500	50	6 V	1.5	0.3
3.0 to 3.6	500	50	6 V	1.5	0.3
4.5 to 5.5	500	50	2 x V _{CC}	V _{CC} / 2	0.3

Figure 3. Switching Waveforms

Schematic Diagram (Generic for LCX Family)

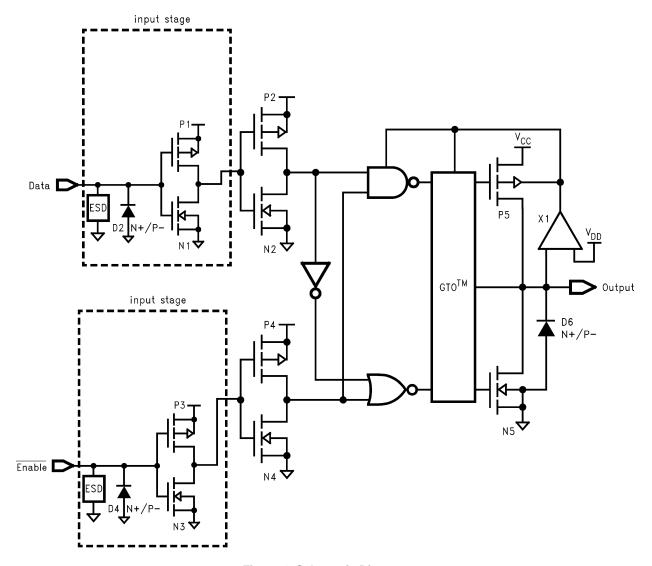


Figure 4. Schematic Diagram

ORDERING INFORMATION

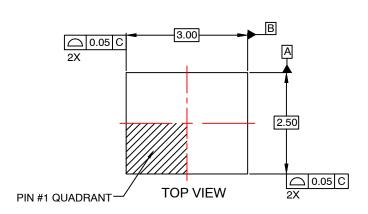
Device	Marking	Package	Shipping [†]
74LCX04MTC	LCX 04	TSSOP-14 (Pb-Free, Halide Free)	96 Units / Tube
74LCX04MTCX	LCX 04	TSSOP-14 (Pb-Free, Halide Free)	2500 Units / Tape & Reel
74LCX04BQX	LCX04	QFN14 (Pb-Free, Halide Free)	3000 Units / Tape & Reel

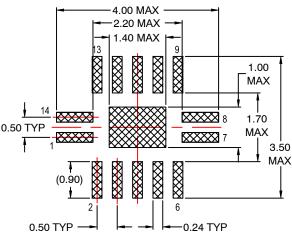
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



QFN14 3.0x2.5, 0.5P CASE 510CB ISSUE O

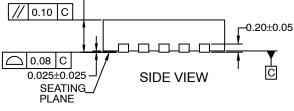
DATE 31 AUG 2016

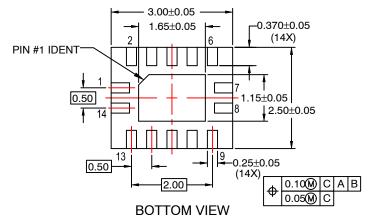




RECOMMENDED LAND PATTERN

0.80±0.05-// 0.10 C _____ 0.08 C c 0.025±0.025 SIDE VIEW SEATING





NOTES:

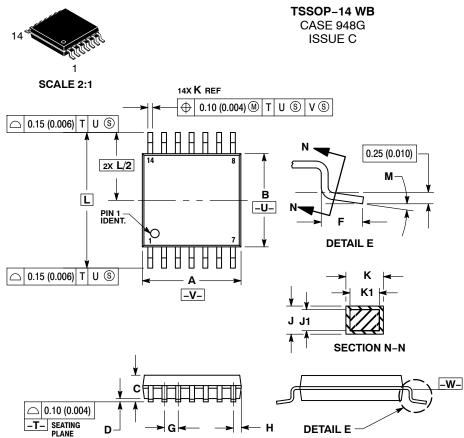
- A. CONFORMS TO JEDEC REGISTRATION MO-241, VARIATION AA
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- D. LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN.

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DATE 17 FEB 2016





- NOTES.

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: MILLIMETER.

 3. DIMENSION A DOES NOT INCLUDE MOLD
- FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 DIMENSION B DOES NOT INCLUDE
- INTERLEAD FLASH OR PROTRUSION.
 INTERLEAD FLASH OR PROTRUSION SHALL
- INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

 DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.

 TERMINAL NUMBERS ARE SHOWN FOR DEEEDENIC OMITY.
- REFERENCE ONLY.
 DIMENSION A AND B ARE TO BE
- DETERMINED AT DATUM PLANE -W-.

	MILLIMETERS		INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	4.90	5.10	0.193	0.200	
В	4.30	4.50	0.169	0.177	
С		1.20		0.047	
D	0.05	0.15	0.002	0.006	
F	0.50	0.75	0.020	0.030	
G	0.65	BSC	0.026 BSC		
Н	0.50	0.60	0.020	0.024	
J	0.09	0.20	0.004	0.008	
J1	0.09	0.16	0.004	0.006	
K	0.19	0.30	0.007	0.012	
K1	0.19	0.25	0.007	0.010	
L	6.40	BSC	0.252 BSC		
м	o o	ρ °	0 °	8 °	

GENERIC MARKING DIAGRAM*



= Assembly Location

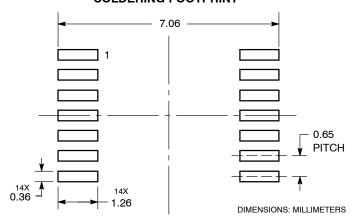
= Wafer Lot = Year

= Work Week W = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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